

ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

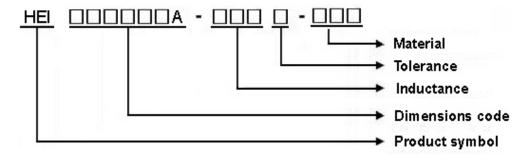
Halogen Free & RoHs Compliance

SPECIFICATION FOR APPROVAL

CUSTOMER:		
CUSTOMER P/N:		
OUR DWG No:		
QUANTITY:	X Pcs. DATE:	2014/06/26
ITEM:	——— HEI252010A-2	 R2M-Q8A
	SPECIFICATION ACCEPTED BY:	
COMPONENT		
ENGINEER		
ELECTRICAL		
ENGINEER		
MECHANICAL		
ENGINEER		
APPROVED		
REJECTED		
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奇力新電子(河南)有限公 Chilisin Electronics (Henan) Co XiuWu Xian, industry gathering JiaoZuo, Henan China Postal Code:454350 TEL:+86-391-717-0682 FAX:+86-391-717-0666	., Ltd. 可 <i>川</i> 新电丁(穌外 area Chilisin Electronics (Suzhou) Co., Ltd. Rd., Suzhou New District, 2350 2356
DRAWN BY 張鈺雯 chang.yuwen	CHECKED BY 張鈺雯 chang.yuwen	APPROVED BY JACKY鍾 jacky.chung

YG14400115

- 1 Scope: This specification applies to Molding power inductors
- 2 Part Numbering: Product Identification



3 Rating:

Operating Temperature: $-4.0 \, ^{\circ}\text{C} \sim 1.2.5 \, ^{\circ}\text{C}$ (Including self - temperature rise)

Storage Temperature: $-40 \, ^{\circ}\text{C} \sim 125 \, ^{\circ}\text{C}$ (after PCB)

 $-\,5\,\text{°C} \sim 3\,\,5\,\text{°C}$,Humidity $\,4\,\,5\,\% \sim 8\,\,5\,\%$ (before PCB)

4 Marking:

No Marking

5 Standard Testing Condition

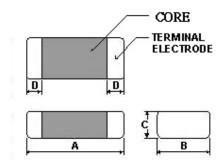
	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35°C)	20±2 ℃
Humidity	Ordinary Humidity(25 to 85% RH)	60 to 70 % RH



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HEI252010A Series Specification

6 Configuration and Dimensions:



Dimensions in mm

TYPE	HEI252010A
Α	2.5±0.3
В	2.0±0.3
С	1.0max
D	0.6±0.3

7 ELECTRICAL CHARACTERISTICS :

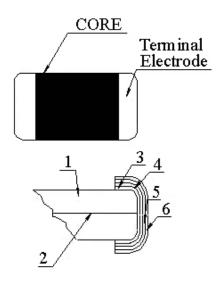
Part No.	Inductance	Test Freq.	Irms(A)	Isat(A)	RDC(mΩ)	SRF(MHz)	Tolerance
	(uH)		Max.(Typ)	Max.(Typ)	Max.(Typ)	Тур	(±%)
HEI252010A-2R2M-Q8A	2.2	2MHz,0.2V	2.5(2.9)	3.2(3.8)	98(87)	40	20

NOTE:

- 1.Operating temperature range $-4~0~{\rm ^{\circ}C} \sim 1~2~5~{\rm ^{\circ}C}$ (Including self temperature rise)
- 2.Irms DC current (A) that will cause an approximate ΔT of 40°C.
- 3.Isat DC current (A) that will cause Lo to drop approximately 30%
- 4.All test data is referenced to 25°C ambient

8 HEI252010A Series

8.1 Construction:



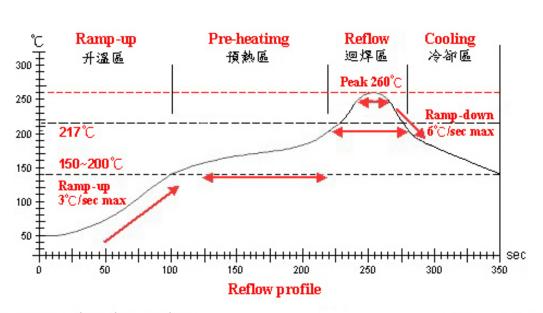
8.2 Material List:

NO	Part	Description
1	Core	Metal Power
2	Wire	Copper wire
3	Sputter/Plating	Cu
4	Silver Electrode	Ag
5	Plating	Ni
6	Plating	Sn

9 Reliability of Molding Power Inductor 1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right	Test device shall be soldered on the substrate
		conditions must not damage	Substrate Dimension: 100x40x1.6mm
		the terminal electrode and the	Deflection: 2.0mm
		ferrite	Keeping Time: 30sec
1-1-2	Vibration		Test device shall be soldered on the substrate
			Oscillation Frequency: 10 to 55 to 10Hz for 1min
			Amplitude: 1.5mm
			Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150°C, 1min
		More than 75% of the terminal	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		electrode should be covered	Solder Temperature: 260±5°ℂ
		with solder.	Immersion Time: 10±1sec
		Inductance: within ±20% of	
		initial value	
1-1-4	Solder ability	The electrodes shall be at	Pre-heating: 150°C, 1min
		least 95% covered with new	Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
		solder coating	Solder Temperature: 245±5°ℂ
			Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination	Test device shall be soldered on the substrate,
		Chip	then apply a force in the direction of the arrow.
		F F	Force : 5N
			Keeping Time: 10±1sec
		Mounting Pad	

No	Item	Specification	Test Method					
1-2-1	Temperature Cycle	Appearance: No damage	One cycle:					
		Inductance:within±20% of	Step	Temperature (℃)	Time (min)			
		initial value	1	-40±3	30			
			2	25±2	2			
			3	125±3	30			
			4	25±2	2			
			Total: 100c	ycles				
			Measured a	after exposure in the room cor	ndition for 24hrs			
1-2-2	Humidity Resistance		Temperature: $60\pm2^{\circ}$ C Relative Humidity: $90 \sim 95\%$ / Time: 500 hrs					
			Measured a	after exposure in the room cor	ndition for 12hrs			
1-2-3	High		Temperatui	re: 85±3°ℂ				
	Temperature Resistance		Relative Hu	ımidity: 0% / Time: 500hrs				
			Measured after exposure in the room condition					
1-2-4	Low		Temperatui	re: -40±3°C				
	Temperature Resistance		Relative Humidity: 0% / Time: 500hrs					
			Measured after exposure in the room condition fo					



Lead-Free(LF) 標準溫度分析範圍

Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T. ~150°C	150° ℃ ~ 200 °℃	217 ℃	260±5°C	Peak Temp. ~ 150°C
標準時間 Time spec.	_	60 ~ 180 sec	60 ~ 150 sec	20 ~ 40 sec	_
實際時間 Time result	_	75 ~ 100 sec	90 ~ 120 sec	20 ~ 35 sec	_

NOTE:

- 1. Re-flow possible times: within 2 times
- 2. Nitrogen adopted is recommended while in re-flow



10 TEST DATA FOR PREPRODUCTION SAMPLES

QF-1419

DESCRIPTION: HEI252010A-2R2M-Q8A										
MEAS. Item	L0 (uH)	L1 (uH)Max.	RDC (mΩ)Max.	SRF(MHz)	A m/m	B m/m	C m/m	D m/m		
Spec Customer	2.20±20%									
Suggest		L0*0.7	97(87typ)	40	2.5±0.3	2.0±0.3	1.0max	0.6±0.3		
Test Freq.	Isat=0A 2MHz 0.2V	Isat=3.2A 2MHz 0.2V								
1	2.15	1.65	88.4	44.03	2.62	2.18	0.98	0.52		
2	2.10	1.60	88.1	35.52	2.62	2.18	0.92	0.52		
3	2.05	1.58	88.7	40.99	2.61	2.17	0.94	0.50		
4	2.03	1.49	87.2	35.52	2.62	2.18	0.96	0.50		
5	2.04	1.54	87.5	40.99	2.62	2.19	0.96	0.54		
6										
7										
8										
9										
10										
11										
12										
13										
14										
15										
X	2.074	1.572	87.98	39.41	2.618	2.18	0.952	0.516		
R	0.12	0.16	1.5	8.51	0.01	0.02	0.06	0.04		
CUSTOMER										
SAMPLE										

TEST INSTRUMENT:

L : Agilent E4991A/HP4287A+16197A RDC : CHEN HWA 502BC / HP4338B Isat : Agilent E4980A+HP42841A

Irms: Agilent 6641 SYSTEM DC POWER SUPPLY

APPEARANCE AND DIMENSIONS:

SPEC: MEET ITEM 6.

TEST METHOD: VISUAL INSPECTION AND MEASURED WITH SILDE CALIPERS.

TESTING CONDITIONS:

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature (15 to 35°ℂ)	20 ± 2 ℃
Humidity	Ordinary Humidity (25 to 85 %RH)	60 to 70 %RH

11 Packaging

11.1 Packaging -Cover tape

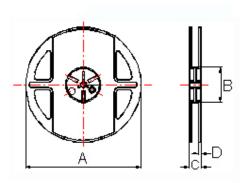
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

TYPE	BULK	PCS/REEL		
HEI252010A	V	3000		

11.3 Reel Dimensions

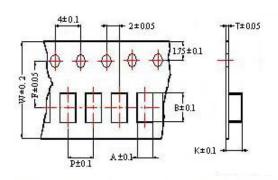


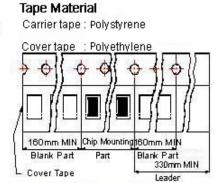
Dimensions in mm

TYPE	Α	В	С	D
HEI252010A	178	60	12	1.5

11 Packaging

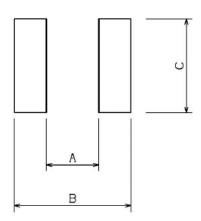
11.4 Tape Dimensions in mm





TYPE	Α	В	Т	W	Р	F	K
HEI252010A	2.25	2.8	0.22	8	4	3.5	1.35

12 Recommended Pattern



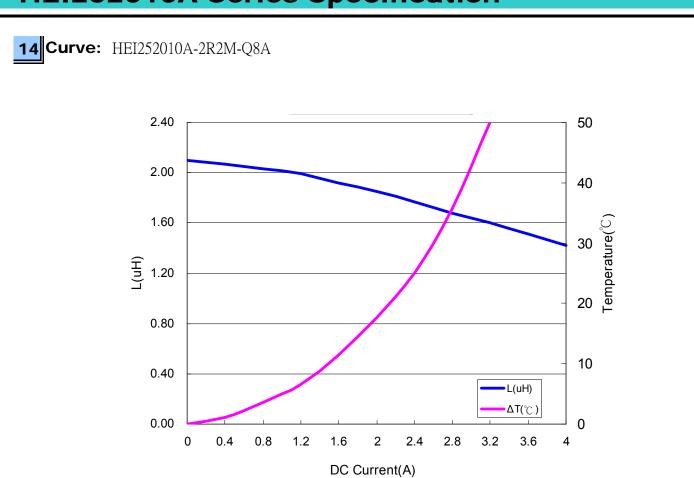
Dimensions in mm

TYPE	Α	В	С
HEI252010A	1.2	2.8	2.0

13 Note:

- 1. Please make sure that your product is has been evaluated and confirmed against your specifications when our product is mounted to your product.
- 2. Do not knock nor drop.
- 3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
- 4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)





单击下面可查看定价,库存,交付和生命周期等信息

>>CHILISIN(奇力新)